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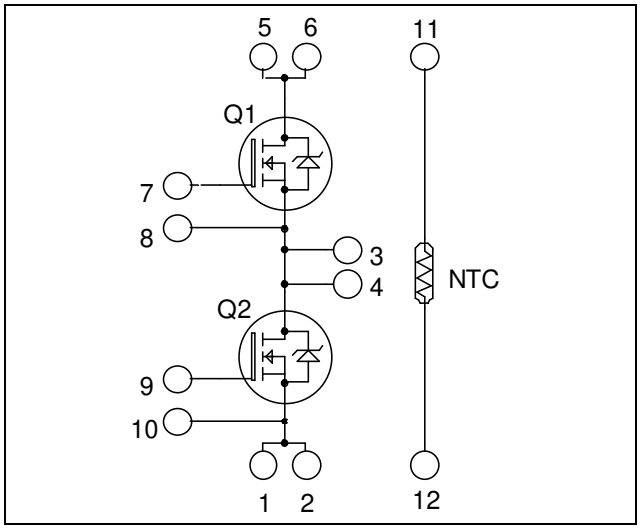
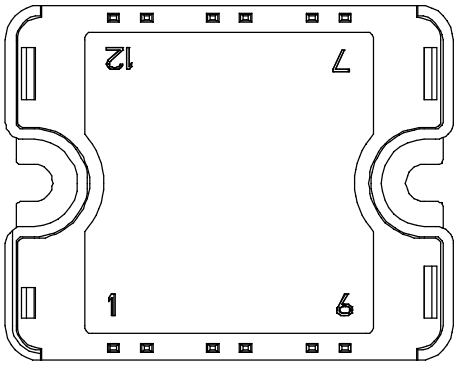
APTM120A65FT1G

Phase leg MOSFET Power Module

V_{DSS} = 1200V
R_{DSon} = 650mΩ typ @ Tj = 25°C
I_D = 16A @ Tc = 25°C





Pins 1/2 ; 3/4 ; 5/6 must be shorted together

Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Power MOS 8™ Fast FREDFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Fast intrinsic reverse diode
  - Avalanche energy rated
  - Very rugged
- Very low stray inductance
  - Symmetrical design
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		1200	V
I_D	Continuous Drain Current	T_c = 25°C	16	A
		T_c = 80°C	12	
I_{DM}	Pulsed Drain current		105	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		780	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	390	W
I_{AR}	Avalanche current (repetitive and non repetitive)		14	A

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 1200V V_{GS} = 0V	T_j = 25°C			250	µA
			T_j = 125°C			1000	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 14A			650	780	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 2.5mA		3	4	5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V				±100	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*	*Min*	*Typ*	*Max*	*Unit*
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		7736		pF
C_{oss}	Output Capacitance			715		
C_{rss}	Reverse Transfer Capacitance			92		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 600V I_D = 14A		300		nC
Q_{gs}	Gate – Source Charge			50		
Q_{gd}	Gate – Drain Charge			140		
$T_{d(on)}$	Turn-on Delay Time	**Resistive switching @ 25°C** V_{GS} = 15V V_{Bus} = 800V I_D = 14A R_G = 2.2Ω		50		ns
T_r	Rise Time			31		
$T_{d(off)}$	Turn-off Delay Time			170		
T_f	Fall Time			48		

Source - Drain diode ratings and characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_S	Continuous Source current (Body diode)		Tc = 25°C			16	A
			Tc = 80°C			12	
V_{SD}	Diode Forward Voltage	V_{GS} = 0V, I_S = - 14A				1.1	V
dv/dt	Peak Diode Recovery ❶					25	V/ns
t_{rr}	Reverse Recovery Time	I_S = - 14A V_R = 100V di_S/dt = 100A/µs	T_j = 25°C			335	ns
			T_j = 125°C			640	
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		1.72		µC
			T_j = 125°C		4.67		

❶ dv/dt numbers reflect the limitations of the circuit rather than the device itself.
I_S ≤ - 14A di/dt ≤ 1000A/µs V_{DD} ≤ 800V T_j ≤ 125°C

Thermal and package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance					0.32	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, I isol<1mA, 50/60Hz			2500			V
T_J	Operating junction temperature range			-40		150	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M4	2.5		4.7	N.m
Wt	Package Weight					80	g

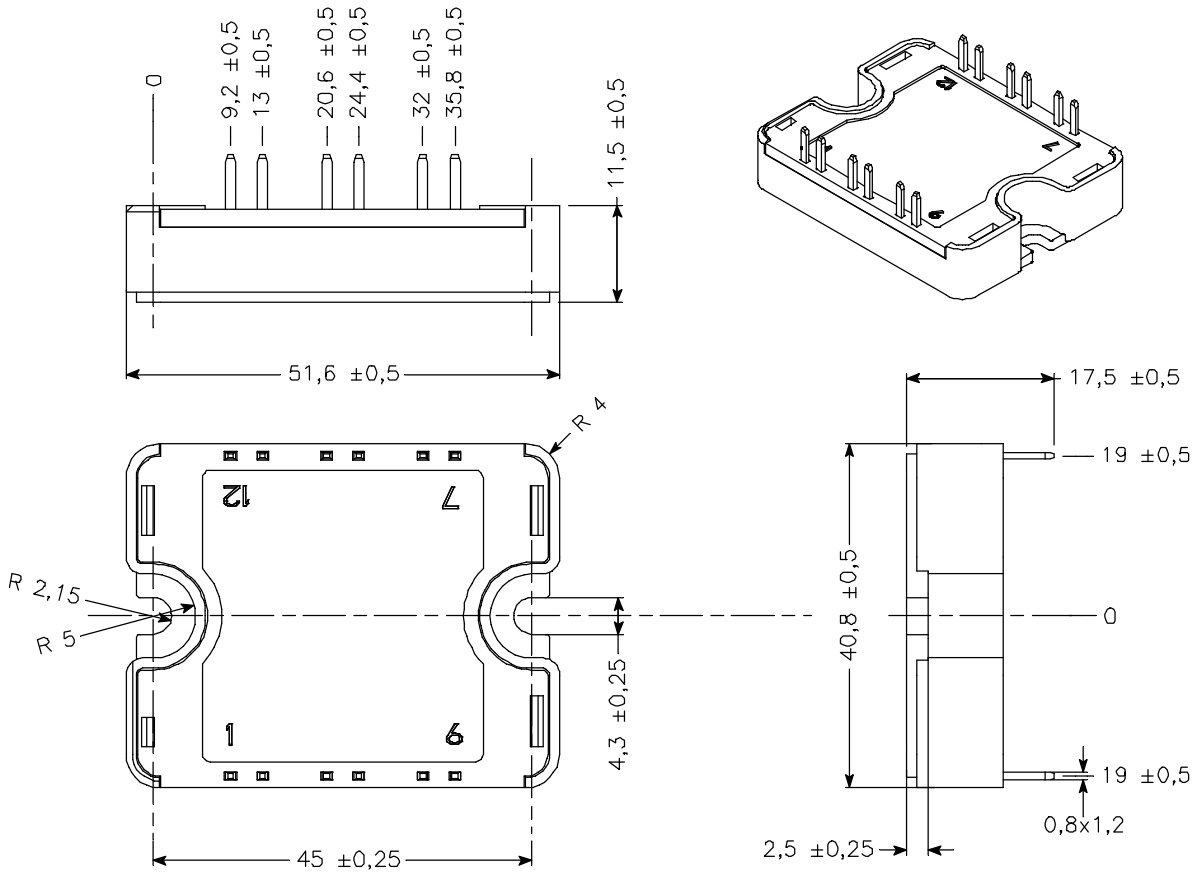
Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C		50		kΩ
$B_{25/85}$	T_{25} = 298.15 K		3952		K

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

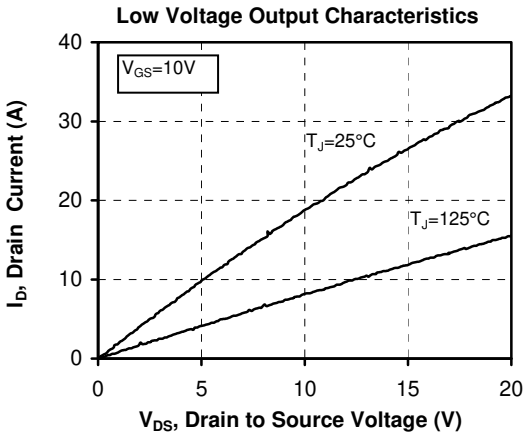
T: Thermistor temperature
R_T: Thermistor value at T

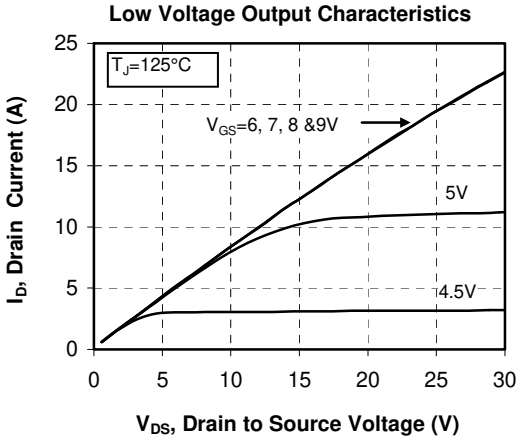
SP1 Package outline (dimensions in mm)

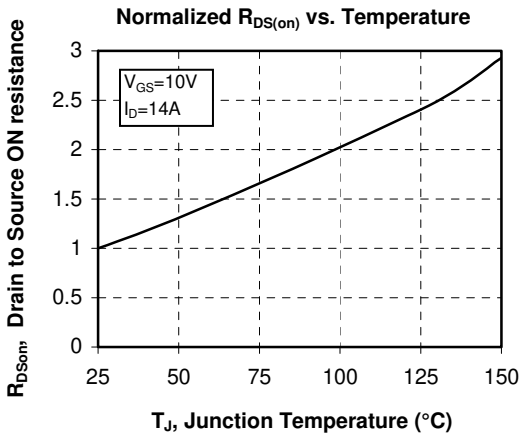


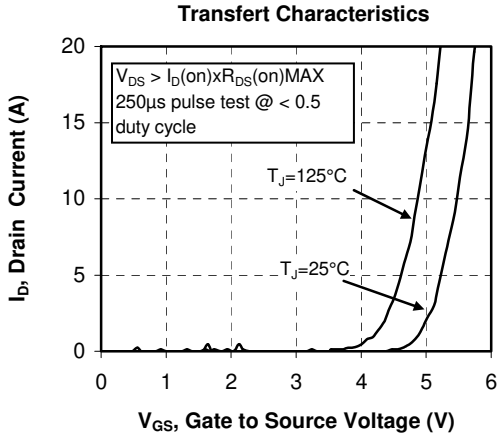
See application note 1904 - Mounting Instructions for SP1 Power Modules on www.microsemi.com

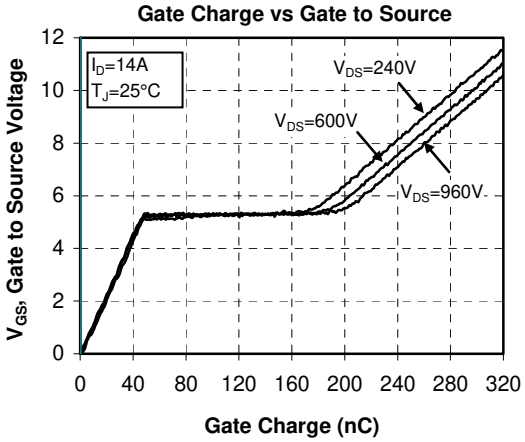
Typical Performance Curve

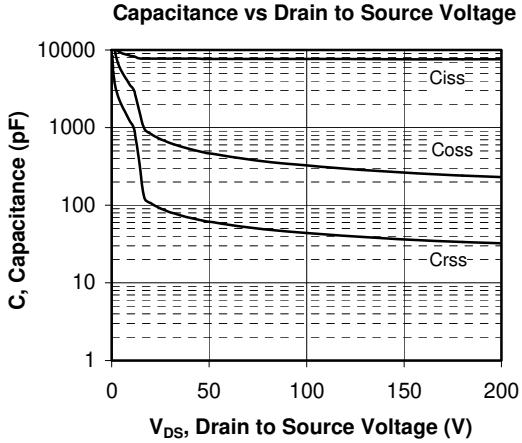




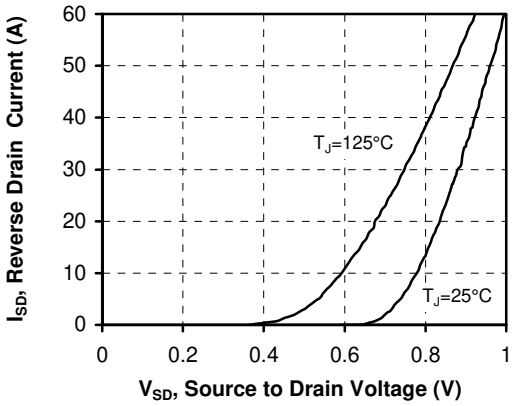








Drain Current vs Source to Drain Voltage



Maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration